

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

SYSTEM AND METHOD OF SMOOTHING MASK SHAPES
FOR IMPROVED PLACEMENT OF SUB-RESOLUTION ASSIST
FEATURES

Application Number :

Confirmation Number:

First Named Applicant: Mark Lavin

Attorney Docket Number: FIS920030323



Art Unit:

Examiner:

Search string: (5821014 or 6303252 or 6413683 or 6492097 or 6495435 or 6519760 or 6541165
or 6627361).pn

US Patent Documents


Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5821014	1998-10-13	Chen et al.			
	2	6303252	2001-10-16	Lin			
	3	6413683	2002-07-02	Liebmann et al.			
	4	6492097	2002-12-10	Chen et al.			
	5	6495435	2002-12-17	Templeton et al.			
	6	6519760	2003-02-11	Shi et al.			
	7	6541165	2003-04-01	Pierrat			
	8	6627361	2003-09-30	Bula et al.			

Signature

Examiner Name

Date






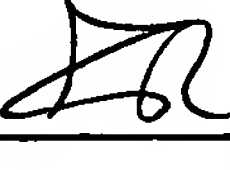
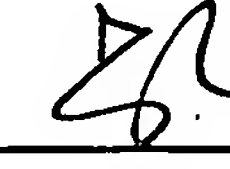


8-06

FORM PTO-1449 (Modified)	ATTY. DOCKET NO. FIS920030323US1	SERIAL NO. 10/707,778
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	APPLICANT: LAVIN ET AL.	
(Use several sheets if necessary)	FILING DATE: 01-12-04	GROUP: 1756

REFERENCE DESIGNATION OTHER ART

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER INITIALS		
	AJ	Granik et al., "Two-dimensional G-MEEF Theory and Applications," Proceedings of SPIE - The International Society for Optical Engineering v.4754 2002 p.146-155.
	AI	LaCour et al., "Model-Based OPC For Sub-Resolution Assist Feature Enhanced Layouts," Proceedings of SPIE - The International Society for Optical Engineering, 2002.
	AK	Joesten et al., "The Effect Of Scattering Bar Assist Features In 193 Nm Lithography," Optical Microlithography XV. Proceedings of SPIE - The International Society for Optical Engineering v.4691 II 2002 p.861-870.
	AL	Shi et al., "Understanding The Forbidden Pitch Phenomenon And Assist Feature Placement," Metrology, Inspection, and Process Control for Microlithography XVI. Proceedings of SPIE - The International Society for Optical Engineering v.4689 II 2002 p.985-996.
	AM	Reblinksy et al., "Lithographic Comparison Of Assist Feature Design Strategies," Optical Microlithography XV Santa Clara, CA, USA 5-8 March 2002.
	AN	Smith, "Mutually Optimizing Resolution Enhancement Techniques: Illumination, APSM, Assist Feature OPC, And Gray Bars," Optical Microlithography XIV. Proceedings of SPIE - The International Society for Optical Engineering v.4346 n.1 2001 p.471-485.
	AO	Liebman et al., "Optimizing Style Options For Sub-Resolution Assist Features" Optical Microlithography XIV. Proceedings of SPIE - The International Society for Optical Engineering v.4346 n.1 2001 p.141-152.

EXAMINER 	DATE CONSIDERED 8-06
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

2 of 2

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.

FIS920030323US1-

SERIAL NO.

10/707,778

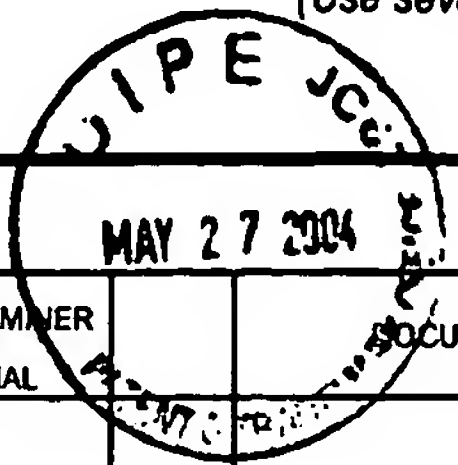
Lavin et al.

FILING

01-12-04

GROUP

1756



U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Chen et al., "Template of Specifications for Assist Feature Script Implementation", Proceedings of SPIE - The International Society for Optical Engineering, v.4754 2002 p.156-166

EXAMINER

[Signature]

DATE CONSIDERED

8-06

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